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ABSTRACT

A reference wafer (W1) used for accuracy control of an exposure apparatus consists of a substrate (51) having a reference pattern formed on its surface. The reference pattern is made up of a first area (54) having a first amplitude reflectivity and a second area (53) having a second amplitude reflectivity different from the first amplitude reflectivity, and a step between the surface of the first area and the surface of the second area is flattened so as to be about 50nm or less.

Therefore, even in the case where photoresist needs to be coated ultra thin (for example, a film thickness of about 0.3μm or less) on the surface of the reference wafer (W1), coating unevenness of the resist caused by the step between the surface of the first area and the surface of the second area does not occur, and good resist coating characteristic can be obtained. By performing accuracy control of the exposure apparatus using the reference wafer (W1), the overlay accuracy of the exposure apparatus is controlled. As a consequence, accuracy control of high accuracy and high reliability is enabled.



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